

Please replace the paragraph beginning at page 7, line 19, with the following rewritten paragraph:

^{a3} In this embodiment, the covering layer 50 is transparent to UV radiation.

In the Claims:

Please cancel claims 1-18 and 23.

Please amend claims 19-22 to read as follows:

^{a4} 19. (Amended) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit;

Sub Ca a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over a portion of the electronic device such that the electronic device can be at least partially activated from outside of said protective package; and

a projecting portion of elastic material projecting from a surface of the electronic device into the window, the projecting portion being structured to enable the electronic device to be activated through the projecting portion when the electronic device is in use.

20. (Amended) The packaged electronic device according to claim 19 wherein said projecting portion is shaped to form a ring on the electronic circuit.

21. (Amended) The packaged electronic device according to claim 19 wherein said window has tapering walls toward said electronic circuit.

22. (Amended) The packaged electronic device according to claim 19 wherein said projecting portion is surrounded by dyke or barrier formed on a surface of the electronic circuit.

Please add new claims 24-30 to read as follows:

24. The packaged electronic device of claim 19 wherein the electronic circuit includes a proximity sensor.

25. A packaged electronic device ready for electronic use, comprising:
a semiconductor-integrated electronic circuit;
a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over a portion of the electronic device such that the electronic device can be activated from outside of said protective package; and
an elastic protective layer positioned in the window, the protective layer being structured to enable the electronic device to be activated through the protective layer when the electronic device is in use.

26. The packaged electronic device of claim 25, further comprising a membrane positioned between the electronic circuit and the protective layer, the membrane having a concave surface facing the electronic circuit so as to leave a recess between the concave surface and the electronic circuit.

27. The packaged electronic device of claim 25 wherein the protective layer is shaped to form a ring on the electronic circuit.

28. The packaged electronic device of claim 25 wherein the window has walls tapering toward said electronic circuit.

29. The packaged electronic device of claim 25 wherein the protective layer is surrounded by dyke or barrier formed on a surface of the electronic circuit.

30. The packaged electronic device of claim 25 wherein the electronic circuit includes a proximity sensor.